UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/801,987	03/16/2004	Yuko Fukawa	81872.0057	2506
<sup>26021</sup> HOGAN & HA	7590 03/11/200 RTSON L.L.P.	EXAMINER		
1999 AVENUE	OF THE STARS	TAI, XIUYU		
SUITE 1400 LOS ANGELES	S, CA 90067	ART UNIT	PAPER NUMBER	
			1795	
			MAIL DATE	DELIVERY MODE
			03/11/2009	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

## Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)	
10/801,987	FUKAWA ET AL.	
Examiner	Art Unit	

	Xiuyu Tai	1795	
The MAILING DATE of this communication appe	ars on the cover sheet with the c	orrespondence add	ress
THE REPLY FILED <u>04 March 2009</u> FAILS TO PLACE THIS AP	PLICATION IN CONDITION FOR	ALLOWANCE.	
<ol> <li>The reply was filed after a final rejection, but prior to or on application, applicant must timely file one of the following application in condition for allowance; (2) a Notice of Appelor Continued Examination (RCE) in compliance with 37 Coperiods:</li> </ol>	the same day as filing a Notice of A replies: (1) an amendment, affidavited al (with appeal fee) in compliance w	Appeal. To avoid abar ., or other evidence, w with 37 CFR 41.31; or	hich places the (3) a Request
a) The period for reply expires <u>3</u> months from the mailing date	of the final rejection.		
b) The period for reply expires on: (1) the mailing date of this A no event, however, will the statutory period for reply expire to Examiner Note: If box 1 is checked, check either box (a) or (MONTHS OF THE FINAL REJECTION. See MPEP 706.07(1)	ater than SIX MONTHS from the mailing b). ONLY CHECK BOX (b) WHEN THE f).	date of the final rejection FIRST REPLY WAS FIL	n. LED WITHIN TWO
Extensions of time may be obtained under 37 CFR 1.136(a). The date have been filed is the date for purposes of determining the period of extunder 37 CFR 1.17(a) is calculated from: (1) the expiration date of the set forth in (b) above, if checked. Any reply received by the Office later may reduce any earned patent term adjustment. See 37 CFR 1.704(b). NOTICE OF APPEAL	ension and the corresponding amount on hortened statutory period for reply origing than three months after the mailing date	of the fee. The appropria nally set in the final Offic	ate extension fee e action; or (2) as
2. The Notice of Appeal was filed on A brief in comp filing the Notice of Appeal (37 CFR 41.37(a)), or any exter Notice of Appeal has been filed, any reply must be filed with AMENDMENTS	nsion thereof (37 CFR 41.37(e)), to	avoid dismissal of the	
3. The proposed amendment(s) filed after a final rejection, be	out prior to the data of filing a brief	will not be entered be	201100
(a) ☐ They raise new issues that would require further cor (b) ☐ They raise the issue of new matter (see NOTE below)  (c) ☐ They are not deemed to place the application in bether the proposed affection, they are not deemed to place the application in bether the proposed affection, they are not deemed to place the application in bether they are not deemed to place the application in bether they are not deemed to place the application in bether they are not deemed to place the application in bether they are not deemed to place the application in bether they are not deemed to place the application in bether they are not deemed to place the application in bether they are not deemed to place the application in bether they are not deemed to place the application in the proposed affection.	nsideration and/or search (see NOT w);	E below);	
appeal; and/or			
(d) ☐ They present additional claims without canceling a c NOTE: (See 37 CFR 1.116 and 41.33(a)).	corresponding number of finally reje	ected claims.	
4. The amendments are not in compliance with 37 CFR 1.12	21. See attached Notice of Non-Cor	mpliant Amendment (F	PTOL-324).
5. Applicant's reply has overcome the following rejection(s):		(.	
6. Newly proposed or amended claim(s) would be all non-allowable claim(s).		imely filed amendmer	t canceling the
7.  For purposes of appeal, the proposed amendment(s): a) [ how the new or amended claims would be rejected is prov The status of the claim(s) is (or will be) as follows: Claim(s) allowed:		be entered and an ex	xplanation of
Claim(s) objected to: Claim(s) rejected: <u>25-33</u> . Claim(s) withdrawn from consideration:			
AFFIDAVIT OR OTHER EVIDENCE			
<ol> <li>The affidavit or other evidence filed after a final action, but because applicant failed to provide a showing of good and was not earlier presented. See 37 CFR 1.116(e).</li> </ol>			
<ol> <li>The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to o showing a good and sufficient reasons why it is necessary</li> </ol>	vercome <u>all</u> rejections under appea and was not earlier presented.  Se	ıl and/or appellant fails ee 37 CFR 41.33(d)(1)	s to provide a
10. ☐ The affidavit or other evidence is entered. An explanation REQUEST FOR RECONSIDERATION/OTHER	n of the status of the claims after er	ntry is below or attache	ed.
The request for reconsideration has been considered but See Continuation Sheet.	t does NOT place the application in	condition for allowand	ce because:
<ul><li>12. ☐ Note the attached Information <i>Disclosure Statement</i>(s). (</li><li>13. ☐ Other:</li></ul>	PTO/SB/08) Paper No(s)		
/Alexa D. Neckel/			
Supervisory Patent Examiner, Art Unit 1795			

Continuation of 11. does NOT place the application in condition for allowance because: In response to the arguments the Tsuzuki et al fails to teach a step of connecting the lead to the electrodes by melting the second dolder layer that has a lower melting point than the first solder layer as cited in claim 25, Tsuzuki et al teaches the metal member electrically and mechanically connected a plurality of solar cells comprising copper coated with any metal selected from at least silver, solder and nickel (col. 6, line 8-12). The metal member (i.e. a silver coated copper foil) is connected to the bus bar 102 on the collector electrode by soldering (col. 7, line 1-5) and to the back side of electrode (i.e. soft copper foil) by soldering (col. 14, line 7-11). The materials suitable for the collector electrode include metals such as solders (col. 12, line 27-29). Since the solder layers at the collector electrode/metal member and backelectrode/metal member are different, the soldering temperature will be different. It is known in the art that soldering is carried out by melting a soler layer. Therefore, Tsuzuki inherently teaches to connect the metal member to electrodes by melting diffeternt soler layers. With respect to the teaching of Wood, it also indicates that different solder alloy has different temperature that aids in the assembly of the semiconductor module.